

.025 SQ SOCKET HLE SERIES

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HLE

Insulator Material:
Black Liquid
Crystal Polymer

RILE NO. E111594

US **Contact Material:** BeCu Plating:

Au over 50μ" (1,27μm) Ni Current Rating:

Current Hating: 2.5A @ 80°C ambient Operating Temp Range: -55°C to +125°C Insertion Depth: (1,78mm) .070" to (3,43mm) .135", pass-through, or (2,59mm) .102" min for bottom entry Insertion Force:

(Single contact only) 2oz (0,56N) avg. Withdrawal Force: (Single contact only) 1.6oz (0,44N) avg. **RoHS Compliant:**

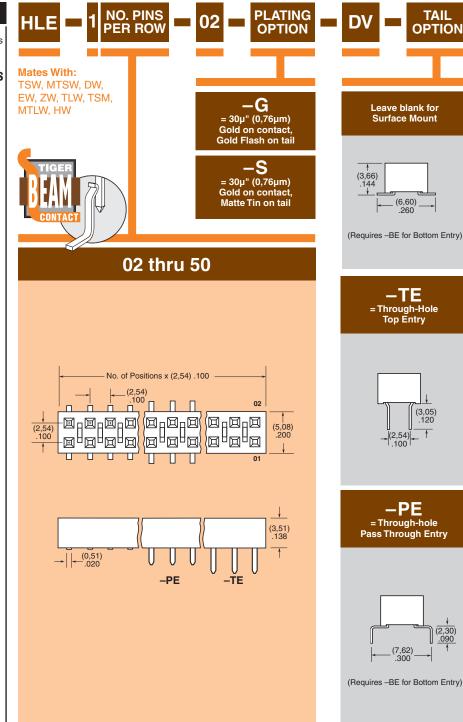
Processing:

Note: Some lengths,

styles and options are non-standard, non-returnable.

Max Processing Temp: 230°C for 60 seconds, or 260°C for 20 seconds 3x Lead-Free Solderable:

SMT Lead Coplanarity: (0,10mm) .004" max (02-20) (0,15mm) .006" max (21-50)



-BE = Bottom Entry (Requires Surface Leave blank for Mount or -PE) **Surface Mount** = Alignment Pin (4 positions min.)

OPTION

-TE

= Through-Hole Top Entry

(3,05)

-PE

= Through-hole

(2,30)

Metal or plastic at Samtec discretion (1,27).050 (1.60)

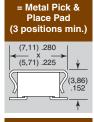
OTHER

OPTION

–LC = Locking Clip (2 positions min.)



= (6,50mm) .256" DIA Polyimide Film Pick & Place Pad (3 positions min.) Not available with -TE or -PE tail option



= Tape & Reel Packaging (29 positions max.)